# **TOSHIBA**

TC57H1024AD-85, -100

### SILICON STACKED GATE CMOS

# 65,536 WORD x 16 BIT CMOS UV ERASABLE AND ELECTRICALLY PROGRAMMABLE READ ONLY MEMORY

### Description

The TC57H1024AD is a 65,536 word x 16 bit CMOS ultraviolet light erasable and electrically programmable read only memory. The TC57H1024AD has a JEDEC standard pin configuration. This product is available in a 40-pin standard cerdip package.

The TC57H1024AD is fabricated using CMOS technology. Advanced circuit techniques result in both high speed and low power features with a maximum operating current of 40mA/1MHz and access times of 85ns/100ns.

The programming time of the TC57H1024AD (except for EPROM programmer overhead) is only 7 seconds when using the high speed programming algorithm.

#### **Features**

Peripheral circuit : CMOS
Memory cell : NMOS

· Access time

	-85	-100
t <sub>ACC</sub>	85ns	100ns
V <sub>DD</sub>	5V±5%	5V±10%

Low power dissipation

- Active : 40mA/1MHz - Standby : 100uA

Single 5V power supply

Fully static operation

High speed programming mode : t<sub>PW</sub> = 0.1ms

• Inputs and outputs TTL compatible

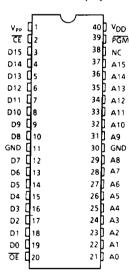
JEDEC standard 40-pin DIP cerdip package

: WDIP40-G-600A

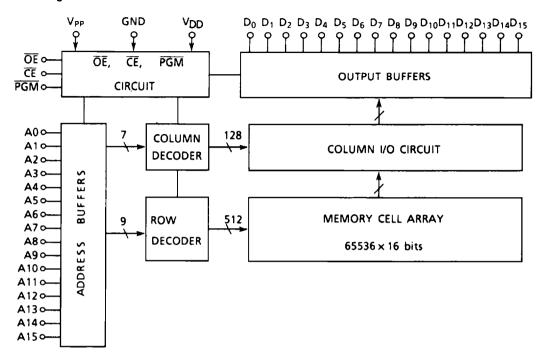
### Pin Names

A0 ~ A15	Address Inputs
D0 ~ D15	Outputs (Inputs)
CE	Chip Enable Input
ŌĒ	Output Enable Input
PGM	Program Control Input
V <sub>DD</sub>	Power Supply Voltage (+5V)
V <sub>PP</sub>	Program Supply Voltage
GND	Ground
NC	No Connection

### Pin Connection (Top View)



# **Block Diagram**



### **Operating Mode**

MODE	PGM	CE	ŌĒ	V <sub>PP</sub>	V <sub>DD</sub>	D0 ~ D15	POWER	
Read	Н	L	L			Data Out	A -45	
Output Deselect	•	•	н	5V	5V	High Impedance	Active	
Standby	*	Н	Н +			High Impedance	Standby	
Program	L	Ł	Н			Data In		
Program Inhibit	*	Н	*	12.75V	6.25V	High Impedance	<b>A A</b>	
- Togram millor	I	L	Н	12./50	6.23V	High Impedance	Active	
Program Verify	Н	L	L	]		Data Out		

<sup>\*</sup>HorL

#### **Maximum Ratings**

SYMBOL	ITEM	RATING	UNIT	
$V_{DD}$	Power Supply Voltage	-0.6 ~ 7.0		
V <sub>PP</sub>	Program Supply Voltage	-0.6 ~ 14.0		
V <sub>IN</sub>	Input Voltage	-0.6 ~ 7.0	→     ∨	
V <sub>IN</sub> (A9)	Input Voltage (A9)	-0.6 ~ 13.5		
V <sub>I/O</sub>	Input/Output Voltage	-0.6 ~ V <sub>DD</sub> + 0.5	┪	
PD	Power Dissipation	1.5	w	
T <sub>SOLDER</sub>	Soldering Temperature • Time	260 • 10	°C • sec	
T <sub>STRG</sub> Storage Temperature		-65 ~ 125		
T <sub>OPR</sub> Operating Temperature		0 ~ 70	⊢ °C	

# Read Mode

# **DC Recommended Operating Conditions**

SYMBOL	PARAMETER	TC57H1000AD/1001AD-85 TC57H1000AD/1001AD-100			AD-100	UNIT		
	STMBUL	PANAMEIEN	MIN.	TYP.	MAX.	MIN.	TYP.	P. MAX.
V <sub>IH</sub>	Input High Voltage	2.2	-	V <sub>DD</sub> + 0.3	2.2	_	V <sub>DD</sub> + 0.3	
V <sub>IL</sub>	Input Low Voltage	-0.3	_	0.8	-0.3	_	0.8	\ <sub>V</sub>
V <sub>DD</sub>	Power Supply Voltage	4.75	5.00	5.25	4.5	5.00	5.50	"
V <sub>PP</sub>	Program Supply Voltage	0	_	V <sub>DD</sub> + 0.6	0	-	V <sub>DD</sub> + 0.6	

# DC Characteristics (Ta = 0 ~ 70°C)

SYMBOL	PARAMETER	TEST CON	IDITION	MIN.	TYP.	MAX.	UNIT
ILI	Input Leakage Current	V <sub>IN</sub> = 0 ~ V <sub>DD</sub>	V <sub>IN</sub> = 0 ~ V <sub>DD</sub>		-	±10	μА
,	Operation Correct	CE = 0V	t <sub>cycle</sub> = 85ns	-	-	60	
DDO	Operating Current	I <sub>OUT</sub> = 0mA	t <sub>cycle</sub> = 1µs	_		40	mA
I <sub>DDS1</sub>	Standby Correct	CE = V <sub>IH</sub>		-	_	1	
I <sub>DDS2</sub>	Standby Current	<u>CE</u> = V <sub>DD</sub> - 0.2V		-	-	100	μА
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -400μA		2.4	-	-	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.1mA	I <sub>OL</sub> = 2.1mA		-	0.4	☐ <b>'</b>
I <sub>PP1</sub>	V <sub>PP</sub> Current	V <sub>PP</sub> = 0V ~ V <sub>DD</sub> ±6	$V_{PP} = 0V \sim V_{DD} \pm 0.6V$		-	±10	
ILO	Output Leakage Current	V <sub>OUT</sub> = 0.4V ~ V <sub>E</sub>	)D	_	-	±10	<u>μ</u> Α

# AC Characteristics (Ta = 0 ~ 70°C, $V_{PP}$ = 0V ~ $V_{DD}$ + 0.6V)

SYMBOL	DADAMETED	TC57H1000A	D/1001AD-85	TC57H1000A	LIMIT	
	PARAMETER	MIN.	MAX.	MIN.	MAX.	UNIT
t <sub>ACC</sub>	Address Access Time	-	85	_	100	
t <sub>CE</sub>	CE to Output Valid	_	85	-	100	
toE	OE to Output Valid	-	45	_	50	T
t <sub>DF1</sub>	CE to Output in High-Z	-	30	_	50	ns ns
t <sub>DF2</sub>	OE to Output in High-Z	-	30	-	50	
toH	Output Data Hold Time	5	_	10	_	

### **AC Test Conditions**

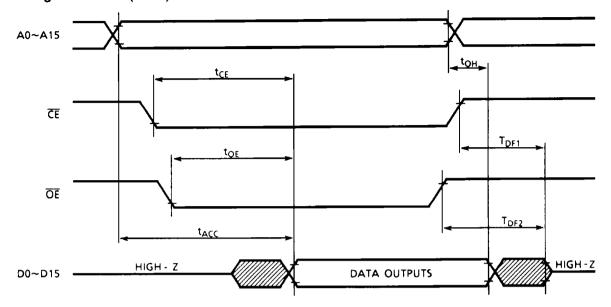
Input Pulse Levels	2.4V/0.45V
Input Pulse Rise and Fall Times	10ns max.
Input Timing Measurement Reference Levels	2.2V/0.8V
Output Timing Measurement Reference Levels	2.0V/0.8V
Output Load	1 TTL Gate and C <sub>L</sub> = 100 pF

# Capacitance\* (Ta = 25°C, f = 1MHz)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	MAX.	UNIT
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V	_	16	-F
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V	-	16	pF

<sup>\*</sup>This parameter is periodically sampled and is not 100% tested.

# Timing Waveforms (Read)



# **High Speed Programming Mode**

# **DC Recommended Operating Conditions**

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V <sub>IH</sub>	Input High Voltage	2.2	-	V <sub>DD</sub> + 0.3	
V <sub>IL</sub>	Input Low Voltage	-0.3	-	0.8	] ,,
$V_{DD}$	Power Supply Voltage	6.00	6.25	6.50	] <b>'</b>
V <sub>PP</sub>	Program Supply Voltage	12.50	12.75	13.00	]

# DC Characteristics (Ta = $25\pm5^{\circ}$ C, $V_{DD}$ = $6.25V\pm0.25V$ , $V_{PP}$ = $12.75V\pm0.25V$ )

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
l <sub>L1</sub>	Input Leakage Current	V <sub>IN</sub> = 0 ~ V <sub>DD</sub>	_		±10	μА
$V_{OH}$	Output High Voltage	I <sub>OH</sub> = -400μA	2.4	- "	_	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.1mA	_	_	0.4	1 <b>'</b>
I <sub>DD</sub>	V <sub>DD</sub> Supply Current	-	_	_	50	4
I <sub>PP2</sub>	V <sub>PP</sub> Supply Current	V <sub>PP</sub> = 13.0V	_		100	m <b>A</b>

# AC Programming Characteristics (Ta = $25\pm5^{\circ}$ C, $V_{DD}$ = $6.25V\pm0.25V$ , $V_{PP}$ = $12.75V\pm0.25V$ )

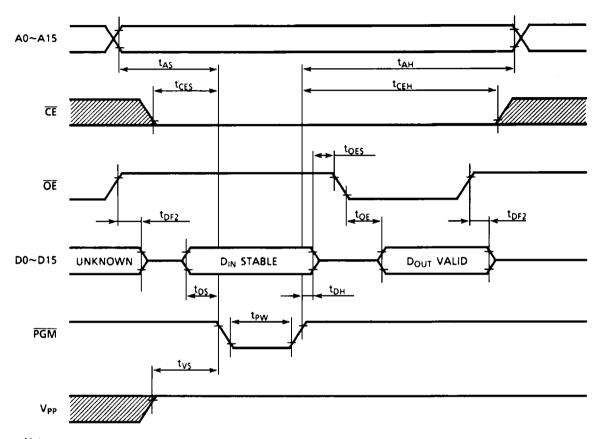
					•	
SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t <sub>AS</sub>	Address Setup Time	-	2	_	_	
t <sub>AH</sub>	Address Hold Time	-	2	-	_	
t <sub>CES</sub>	CE Setup Time	-	2	_	_	
t <sub>CEH</sub>	CE Hold Time	-	2		_	μs
t <sub>DS</sub>	Data Setup Time	-	2	-	-	1
t <sub>DH</sub>	Data Hold Time	-	2	_	-	
t <sub>VS</sub>	V <sub>PP</sub> Setup Time	_	2	-	-	
t <sub>PW</sub>	Program Pulse Width	_	0.095	0.1	0.105	ms
t <sub>OE</sub>	OE to Output Valid	-	-	_	500	
t <sub>DF2</sub>	OE to Output in High-Z	CE = VIL	_	-	150	ns
toes	OE Setup Time	_	2	-	_	μs

# **AC Test Conditions**

input Pulse Levels	2.4V/0.45V
Input Pulse Rise and Fall Times	10ns max.
Input Timing Measurement Reference Levels	2.2V/0.8V
Output Timing Measurement Reference Levels	2.0V/0.8V
Output Load	1 TTL Gate and C <sub>L</sub> = 100 pF

# **Timing Waveforms (Program)**

### **High Speed Programming Mode**



### Notes:

- 1.  $V_{DD}$  must be applied simultaneously or before  $V_{PP}$  and cut off simultaneously or after  $V_{PP}$
- 2. Removing the device from a programming socket and replacing the device in the socket while V<sub>PP</sub> = 12.75V may cause permanent damage to the device.
- 3. The  $V_{PP}$  supply voltage is permitted to be up to 14V for programming. Voltages over 14V should not be applied to the  $V_{PP}$  terminal. When the programming voltage is applied to the  $V_{PP}$  terminal, the overshoot voltage should not exceed 14V.

#### **Erasure Characteristics**

Erasure is achieved by applying shortwave ultraviolet light which has a wavelength of 2537Å (Angstroms) to the chip through the transparent window.

The integrated dose (ultraviolet light intensity [W/cm²] x exposure time [sec.]) necessary for erasure should be a minimum of 15 IW • sec/cm²l.

When the Toshiba sterilizing lamp (GL-15) is used and the device is exposed at a distance of 1 cm from the lamp surface, erasure will be achieved within 60 minutes. Using commercial lamps whose ultraviolet light intensity is  $12000 \, [\mu \text{W/cm}^2]$  will reduce the exposure time to about 20 minutes. (In this case, the integrated dose is  $12000 \, [\mu \text{W/cm}^2] \, \text{x} \, (20 \, \text{x} \, 60) \, [\text{sec}] \cong 15 \, [\text{W} \, \bullet \, \text{sec/cm}^2]$ .)

Erasure begins to occur when exposed to light with a wavelength shorter than 4000Å. Sunlight and fluorescent lights have 3000 ~ 4000Å wavelength components. Therefore, when used under these lighting conditions for extended periods of time, opaque seals should be used (Toshiba EPROM Protect Seal AC901).

#### **Operation Information**

The TC57H1024AD's six operating modes are listed in the following table. Mode selection is achieved by applying TTL level signals to appropriate inputs.

MODE	PIN NAMES	PGM	CE	ŌĒ	V <sub>PP</sub>	V <sub>DD</sub>	D0 ~ D15	POWER	
	Read	Н	L	L			Data Out	Active	
Read Operation (Ta = 0 ~ 70°C)	Output Deselect	•	•	Н	5V	5V	High Impedance	Active	
	Standby	•	Н	*			High Impedance	Standby	
	Program	L	L	Н			Data In	Active	
Program Operation (Ta = 25±5°C)	Program Inhibit	•	Н	*	12.75V	6.25V	Lish Impodence		
		Н	L	Н	1.2.75	0.25	High Impedance		
	Program Verify	Н	L	L	1		Data Out	1	

Notes:  $H = V_{m}$ ,  $L = V_{j}$ ,  $^{*} = V_{jm}$  or  $V_{jj}$ 

#### Read Mode

The TC57H1024AD has three control inputs. The chip enable (CE) input controls the operating power and should be used for device selection while the output enable (OE) and program control (PGM) inputs control the output buffers.

Assuming that  $\overline{CE} = \overline{OE} = V_{|L}$  and  $\overline{PGM} = V_{|H}$ , once the address has stabilized, output data will be valid after the address access time has elapsed. The  $\overline{CE}$  to output valid time  $(t_{\overline{CE}})$  is equal to the address access time  $(t_{\overline{ACC}})$ .

Assuming that  $CE = V_{IL}$ .  $PGM = V_{IH}$ , and that the address has been stable for at least  $t_{ACC}$ , then output data will be valid after  $t_{CE}$  from the falling edge of OE.

#### **Output Deselect Mode**

If  $\overline{CE} = V_{IH}$  or  $\overline{OE} = V_{IH}$ , the outputs will be in a high impedance state.

Therefore, two or more devices can be connected together on a common bus if the output of only one device is enabled. When  $\overline{CE}$  is used for device selection, all deselected devices are in the low power standby mode.

### Standby Mode

The TC57H1024AD has a low power standby mode controlled by the CE signal.

By applying a MOS high level voltage ( $V_{DD}$ ) to the  $\overline{CE}$  input, the TC57H1024AD is placed in the standby mode which reduces the operating current to 100 $\mu$ A and puts the outputs in a high impedance state, independent of the  $\overline{OE}$  input.

#### **Program Mode**

When the TC57H1024AD is initially received by customers, all bits of the device are in the "1" state, which is the erased state. Therefore, the object of the program operation is to introduce "0" data into the desired bit locations.

The TC57H1024AD is in the programming mode when  $V_{PP} = 12.75V$ ,  $\overrightarrow{PGM} = \overrightarrow{CE} = V_{II}$ , and  $\overrightarrow{OE} = V_{IH}$ .

The TC57H1024AD can be programmed at any address location at any time - either individually, sequentially, or at random.

### **Program Verify Mode**

The verify mode is used to check that the desired data has been correctly programmed. The verify mode is activated when  $\overrightarrow{OE} = \overrightarrow{CE} = V_{||}$  and  $\overrightarrow{PGM} = V_{||}$ .

#### **Program Inhibit Mode**

When the programming voltage (+12.75V) is applied to the V<sub>PP</sub> terminal, a high level  $\overline{CE}$  or  $\overline{PGM}$  input inhibits the TC57H1024AD from being programmed.

The programming of two or more EPROMs in parallel with different data is easily accomplished. All inputs except for  $\overline{CE}$  and  $\overline{PGM}$  may be commonly connected, then a  $\overline{TTL}$  low level program pulse is applied to the  $\overline{CE}$  and  $\overline{PGM}$  of the desired device only while a  $\overline{TTL}$  high level signal is applied to the  $\overline{CE}$  of the other devices.

#### **High Speed Programming Mode**

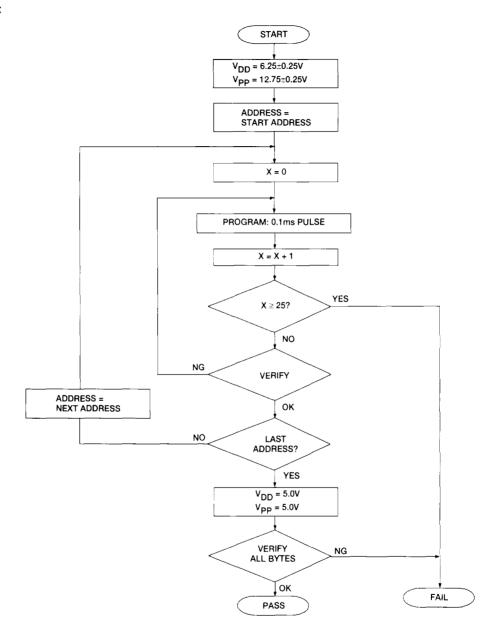
The device is set up in high speed programming mode when the programming voltage (+12.75V) is applied to the  $V_{PP}$  terminal with  $V_{DD} = 6.25V$  and  $\overrightarrow{PGM} = V_{IH}$ .

Programming is achieved by applying a single 0.1ms TTL low level pulse to the PGM input after addresses and data are stable. Then the programmed data is verified by using the program verify mode. If the programmed data is not correct, another program pulse of 0.1ms is applied and then the programmed data is verified. This should be repeated until the data has programmed correctly (max. 25 times).

When programming has been completed, the data in all addresses should be verified with  $V_{DD} = V_{PP} = 5V$ .

# **High Speed Programming Mode**

# Flow Chart



# **Electric Signature Mode**

The electric signature mode allows one to read out a code from the TC57H1024AD which identifies its manufacturer and device type.

The programming equipment may read out the manufacturer code and device code from the TC57H1024AD by using this mode before programming and automatically set the programming voltage (V<sub>PP</sub>) and algorithm.

The electric signature mode is set up when 12V is applied to address line A9 and the rest of the address lines are set to  $V_{\rm IL}$  during a read operation. Data output under these conditions is the manufacturer code. The device code is output when address A0 is set to  $V_{\rm IH}$ .

These two codes possess an odd parity with the parity bit being (D7). The following table shows the electric signature of the TC57H1024AD.

PINS	A0	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	HEX. DATA
Manufacturer Code	V <sub>IL</sub>	*		*		*	*	٠	*	1	0	0	1	1	0	0	0	**98
Device Code	V <sub>IH</sub>	*	*	*	*	*	•	•	•	1	0	0	0	1	0	0	1	**89

\* Don't care

Notes: A9 = 12V±0.5V

A1 ~ A8, A10 ~ A15, CE, OE = V<sub>II</sub>

PGM = VIH